

ELECTRIC CONDUCTIVE TRANSPARENT HIGH BARRIER FILM

Patent Number: JP4210464
Publication date: 1992-07-31
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Requested Patent: JP4210464
Application Number: JP19900341243 19901130
Priority Number(s):
IPC Classification: C23C14/06
EC Classification:
Equivalents: JP2883732B2

Abstract

PURPOSE: To obtain the title film excellent in transparency, gas impermeability and electric conductivity by laminating a thin metal layer and a thin silicon oxide layer on at least one side of a synthetic resin film.
CONSTITUTION: The thin layer (b) of silicon oxide represented by a formula SiO_X (where $1 \leq X < 2$) is formed in about 500-1000 Angstrom thickness on one side or both sides of a film (a) of synthetic resin such as polyethylene terephthalate by electron beam heating and vapor deposition with silicon monoxide as an evaporating source. A metal (alloy) such as Al, Ni or Cr is then vapor-deposited on the surface of the thin layer to form a thin layer (c) in about 30-100 Angstrom thickness. The layers are preferably laminated with the order of (a), (b) and (c) or (a), (c), and (b). The resulting title film is suitable for use as a packing material.

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*elec
conductive*

XP-002169740

AN - 1992-304556 [37]

AP - JP19900341243 19901130 JP19900341243 19901130; [Previous Publ.
J04210464]

CPY - OIKE

DC - L03 M13

FS - CPI

IC - B32B15/08 ; C23C14/06 ; C23C14/08

MC - L03-A01 M13-F

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PN - JP4210464 A 19920731 DW199237 C23C14/06 005pp

- JP2883732B2 B2 19990419 DW199921 C23C14/08 005pp

PR - JP19900341243 19901130

XA - C1992-135539

XIC - B32B-015/08 ; C23C-014/06 ; C23C-014/08

AB - J04210464 The film is composed of (a) synthetic resin film, (b)
silicon oxide (SiO_x $x = 1$ to below 2) thin film layer and (c) metallic
thin film layer, in the order (a)/(b)/(c) or (a)/(c)/(b).

- USE/ADVANTAGE - Used for mfr. of packing materials having electric
conductivity, penetrability and gas-barrier ability(Dwg.0/0)

IW - PRODUCE CONDUCTING TRANSPARENT BARRIER FILM PACK MATERIAL COMPRISE
LAMINATE SYNTHETIC RESIN SILICON OXIDE METALLIC THIN FILM LAYER

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NC - 001

OPD - 1990-11-30

ORD - 1992-07-31

PAW - (OIKE) OIKE KOGYO KK

TI - Prodn. of conductive and transparent barrier film for packing
materials - comprises laminate of synthetic resin, silicon oxide and
metallic thin film layers